

Claims

1. A method for the production of a plurality of optoelectronic semiconductor chips each having a plurality of structural elements with respectively at least one semiconductor layer, the method comprising at least the following method steps:
 - provision of a chip composite base having a substrate and a growth surface;
 - 10 - formation of a mask material layer on the growth surface, with a multiplicity of windows, most of which have an average extent of less than or equal to 1 μm , a mask material being chosen in such a way that a semiconductor material of the semiconductor layer that is to be grown in a later method step essentially cannot grow on said mask material or can grow in a substantially worse manner in comparison with the growth surface;
 - 15 - essentially simultaneous growth of semiconductor layers on regions of the growth surface that lie within the windows; and
 - 20 - singulation of the chip composite base with applied material to form semiconductor chips.
- 25 2. The method as claimed in claim 1, in which the chip composite base has at least one semiconductor layer grown epitaxially onto the substrate and the growth surface is a surface on that side of the epitaxially grown semiconductor layer which is remote from the substrate.
- 30 3. The method as claimed in one of the preceding claims, in which the chip composite base has a semiconductor layer sequence grown epitaxially onto the substrate with an active zone that emits electromagnetic radiation, and the growth surface is a
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surface on that side of the semiconductor layer sequence which is remote from the substrate.

4. The method as claimed in either of claims 1 and 2,
5 in which the structural elements respectively have an epitaxially grown semiconductor layer sequence with an active zone that emits electromagnetic radiation.

5. The method as claimed in one of the preceding
10 claims, in which the mask material has SiO_2 , Si_xN_y or Al_2O_3 .

6. The method as claimed in one of the preceding
claims, in which, after the growth of the semiconductor
15 layers, a layer made of electrically conductive contact material that is transmissive to an electromagnetic radiation emitted by the active zone is applied to the semiconductor layers, so that semiconductor layers of a plurality of structural elements are electrically
20 conductively connected to one another by the contact material.

7. The method as claimed in one of the preceding
claims, in which the average thickness of the mask
25 material layer is less than the cumulated thickness of the semiconductor layers of a structural element.

8. The method as claimed in one of the preceding
claims, in which the mask material layer is at least
30 partly removed after the growth of the semiconductor layers.

9. The method as claimed in one of the preceding
claims, in which, after the growth of the semiconductor
35 layer sequences, a planarization layer is applied over the growth surface.

10. The method as claimed in claim 9, in which a material whose refractive index is lower than that of the semiconductor layers is chosen for the planarization layer.

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11. The method as claimed in claim 9 or 10, in which a material which has dielectric properties is chosen for the planarization layer.

10 12. The method as claimed in one of the preceding claims, in which the growth conditions for the growth of the semiconductor layers are set and/or varied during growth in such a way that semiconductor layers of the structural elements form a lenslike, a
15 truncated-conelike or a polyhedral form.

13. The method as claimed in one of the preceding claims, in which the semiconductor layers are grown by means of metal organic vapor phase epitaxy.

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14. An optoelectronic semiconductor chip, characterized in that it is produced according to a method as claimed in one of the preceding claims.